



低温低噪声读出电子学研制进展

—适用于 $0\nu\beta\beta$ 的nEXO实验

报告人：吴文欢

核探测与核电子学国家重点实验室学术年会

高能所实验物理中心

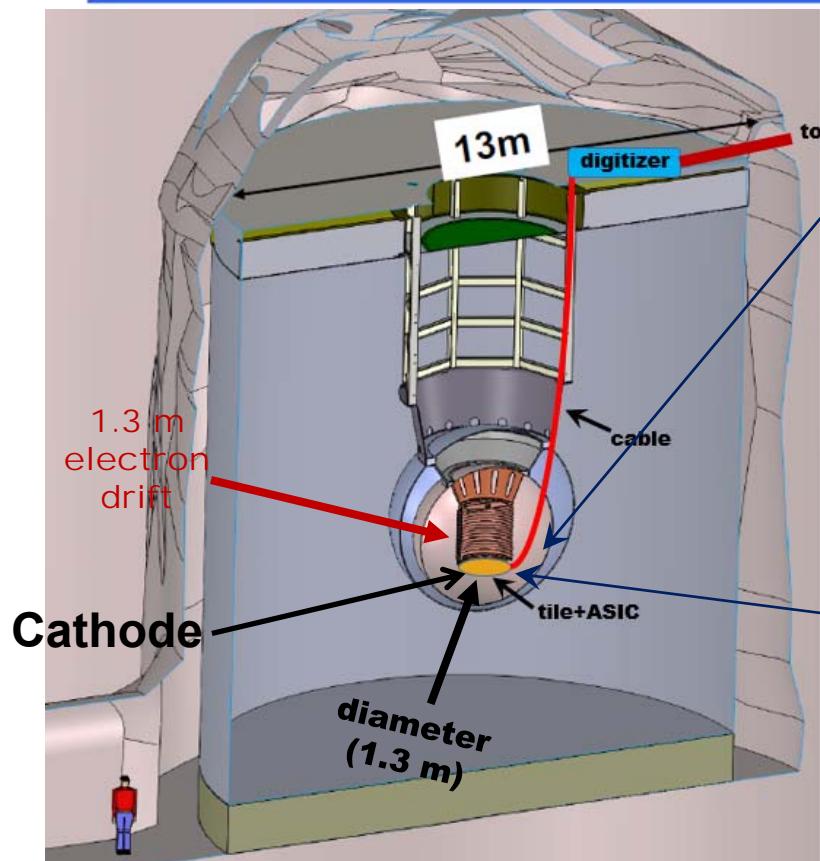
2018/4/26

Outline



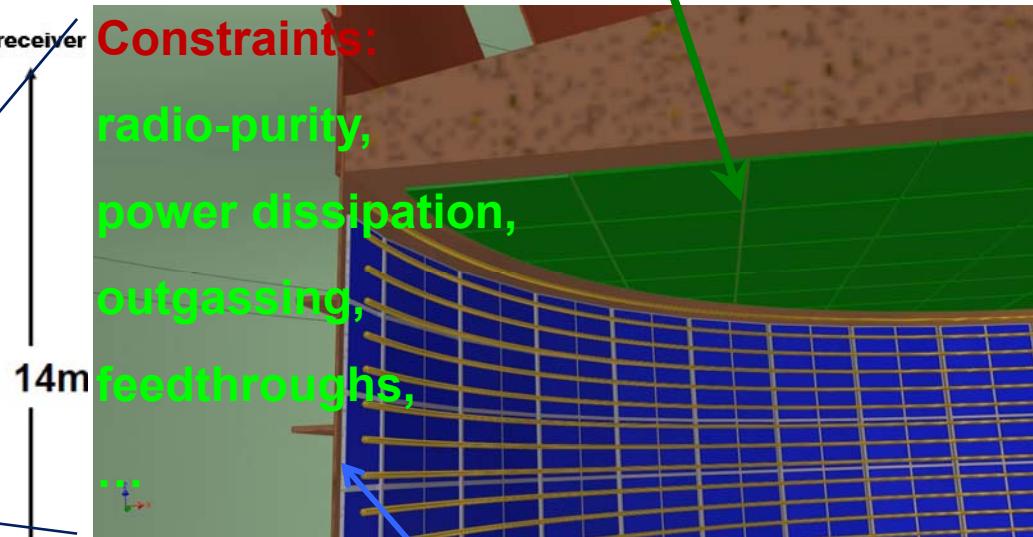
- **R&D status**
 - Brief introduction of the ASIC
 - Chip functionality
 - Several test results
- **Recent efforts**
 - System integration concept
 - Back-end electronics and DAQ system
- **Recent plan**

nEXO TPC 概念设计

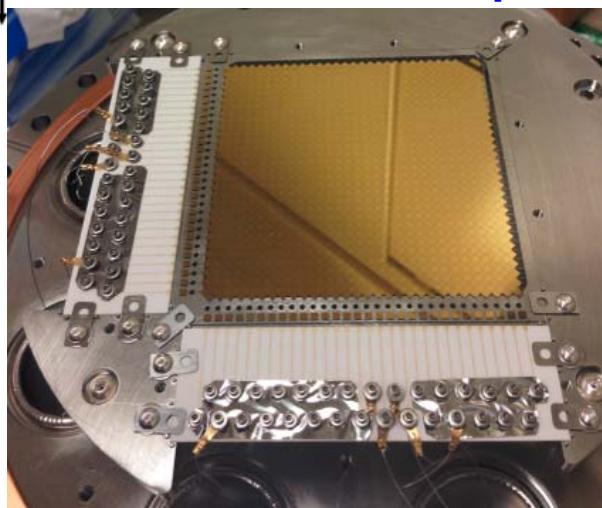


- ~ 5 tonne LXe TPC, 4.7 tonnes of active ^{enr}Xe (90% or higher)
- < 1.0% (σ/E) energy resolution

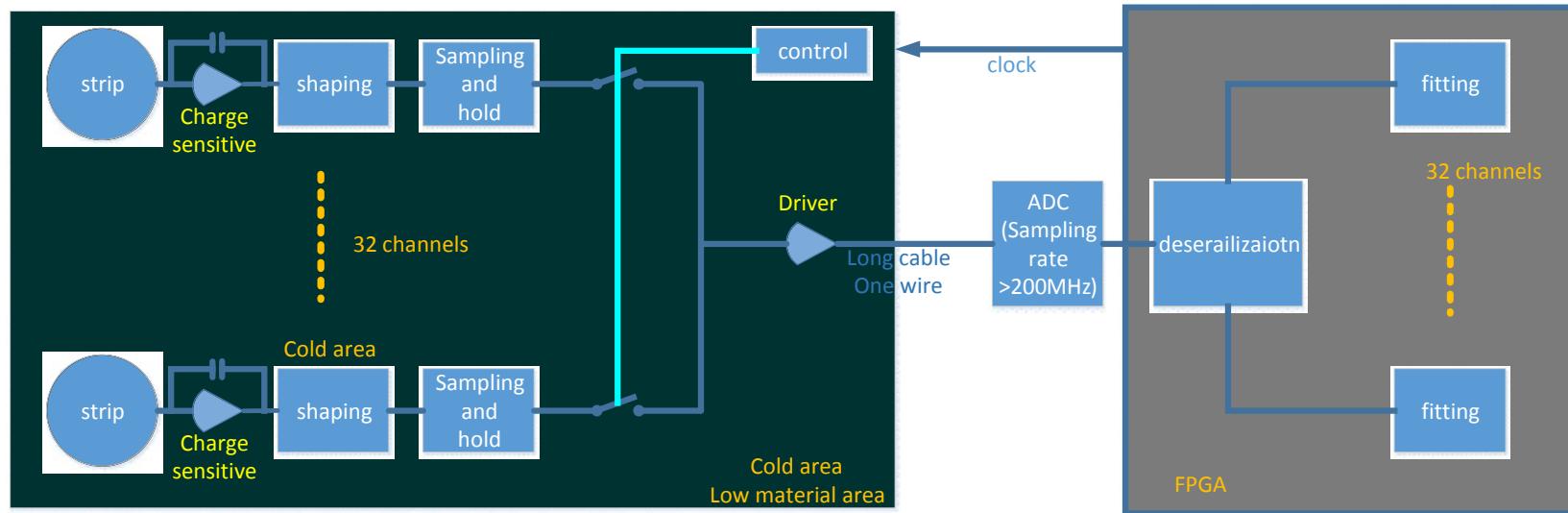
Charge Readout Tiles + ASIC



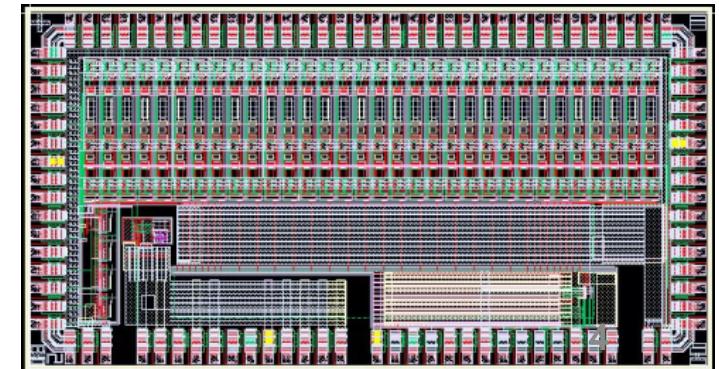
Silicon Photomultipliers (SiPMs) + ASIC



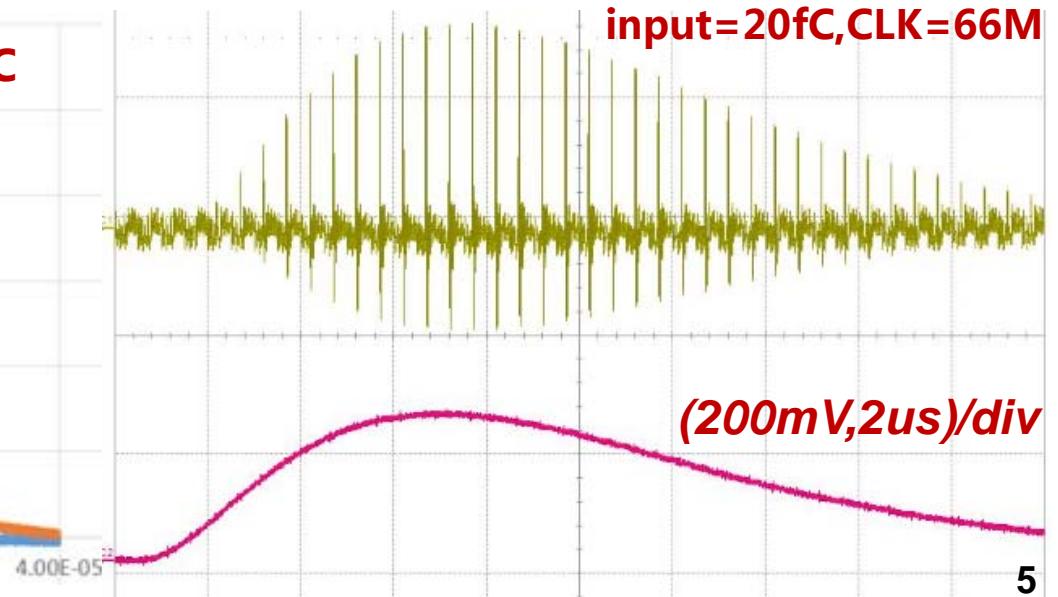
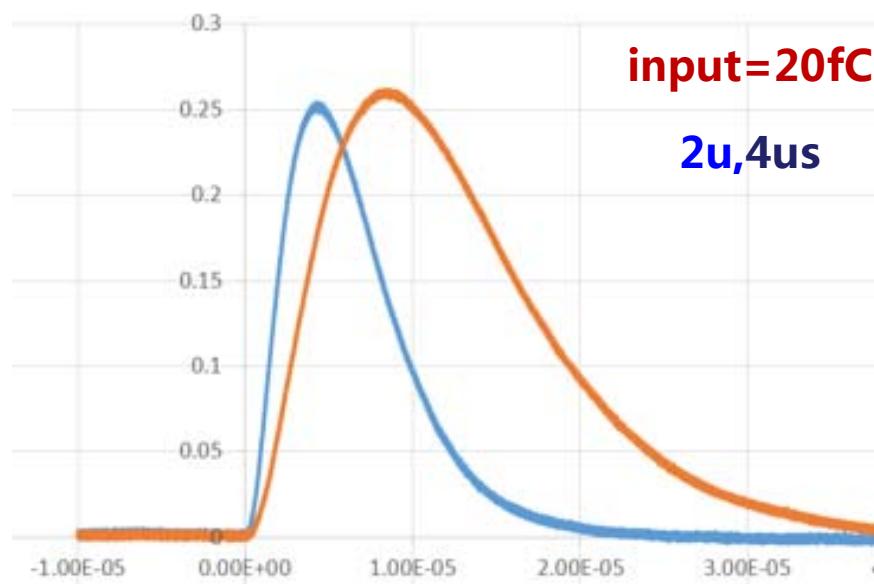
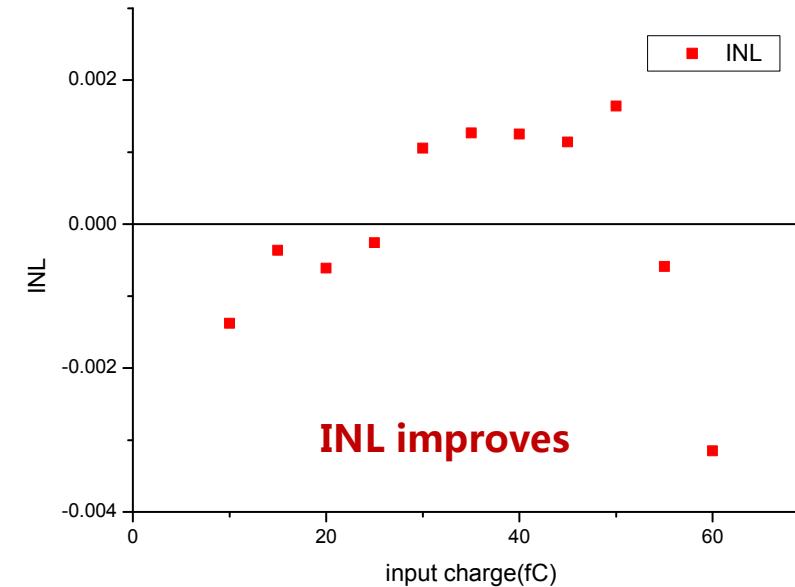
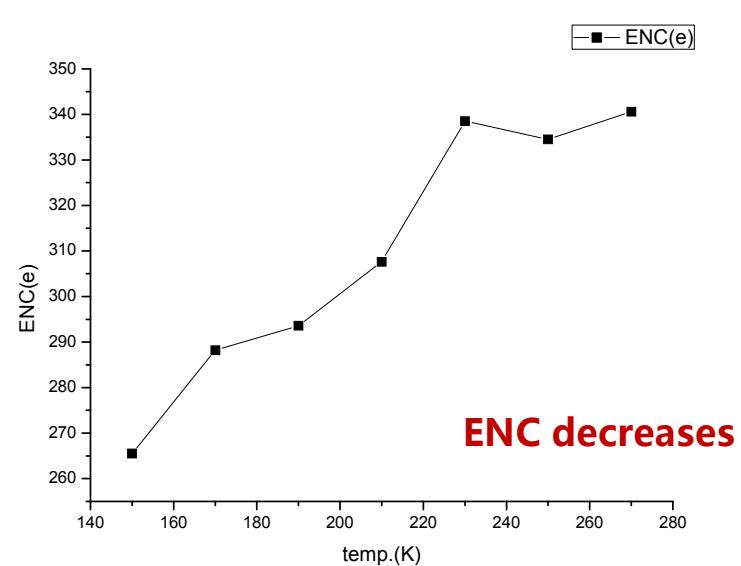
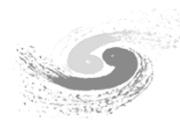
Analog serial readout ASIC



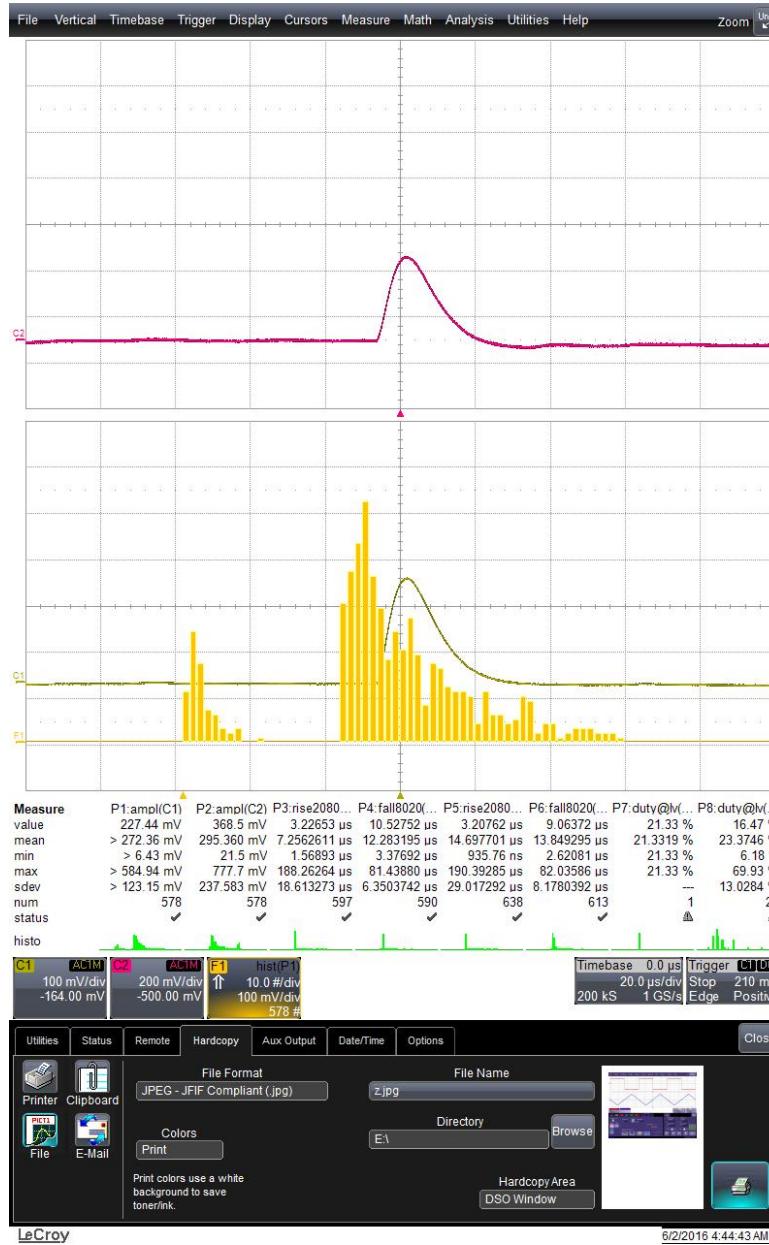
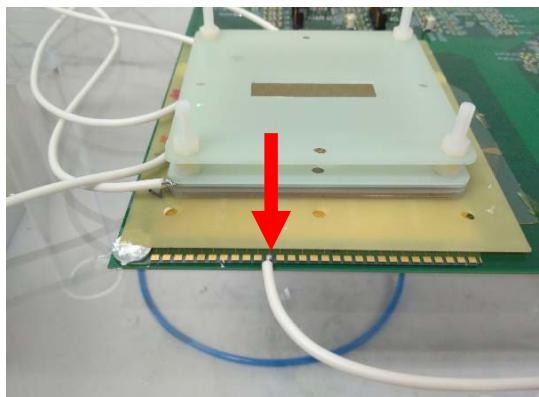
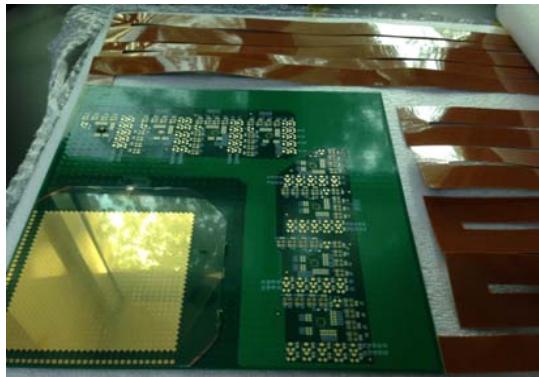
- **32 channels per chip, serial readout channel by channel**
- **ENC down to $190\text{e}@300\text{K}, 20\text{pF(sim.)}$, LVDS CLK(up to 200M)**
- **1output+2power+2clock pin to room temperature**
- **All 100 tiles need:**
 - **2outputs/per tile*100**
 - **2power+2clock**
 - **Reduce cables significantly(background)**



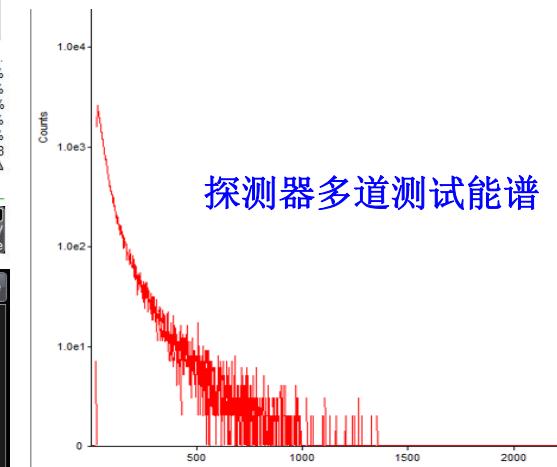
Some measurement results(160K)



与tile联调(带增益、刚挠板)



- 放射源 : ^{90}Sr
- 探测器 : 双层THGEM
- 计数率约百KHz
- 约2m柔性板信号读出
- 随机选取芯片两通道输出
- 波形正常 , 与放射源能谱基本吻合 , 正常工作



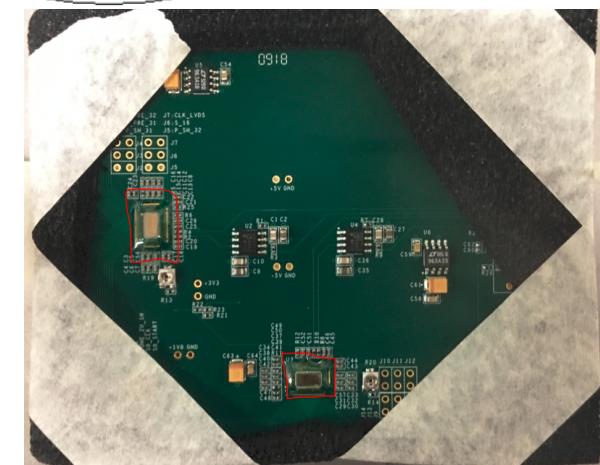
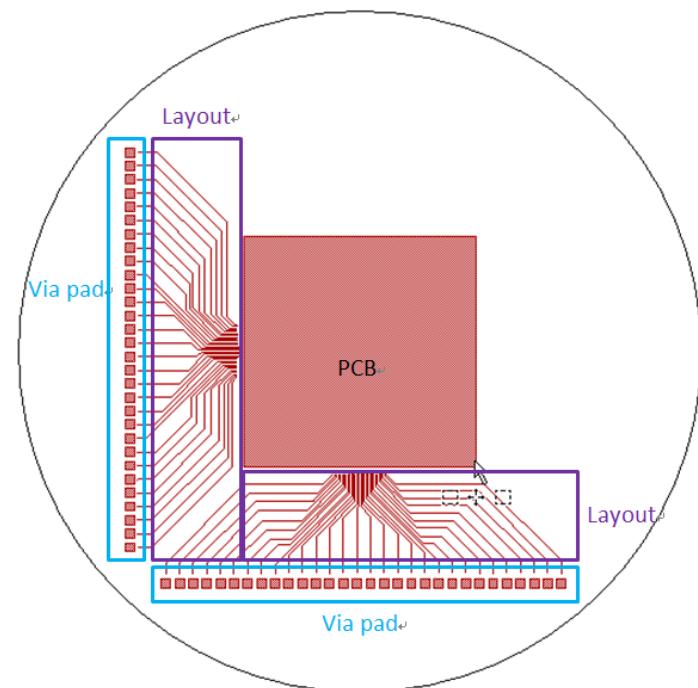
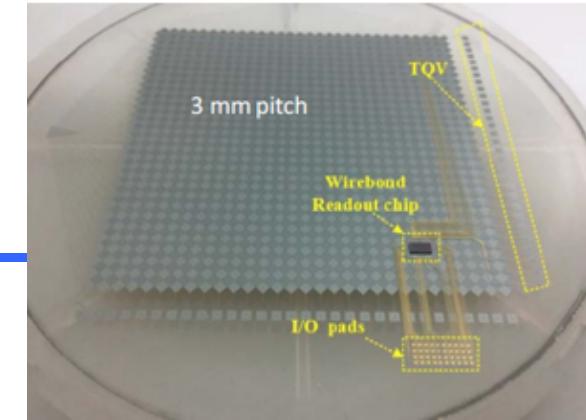
Outline



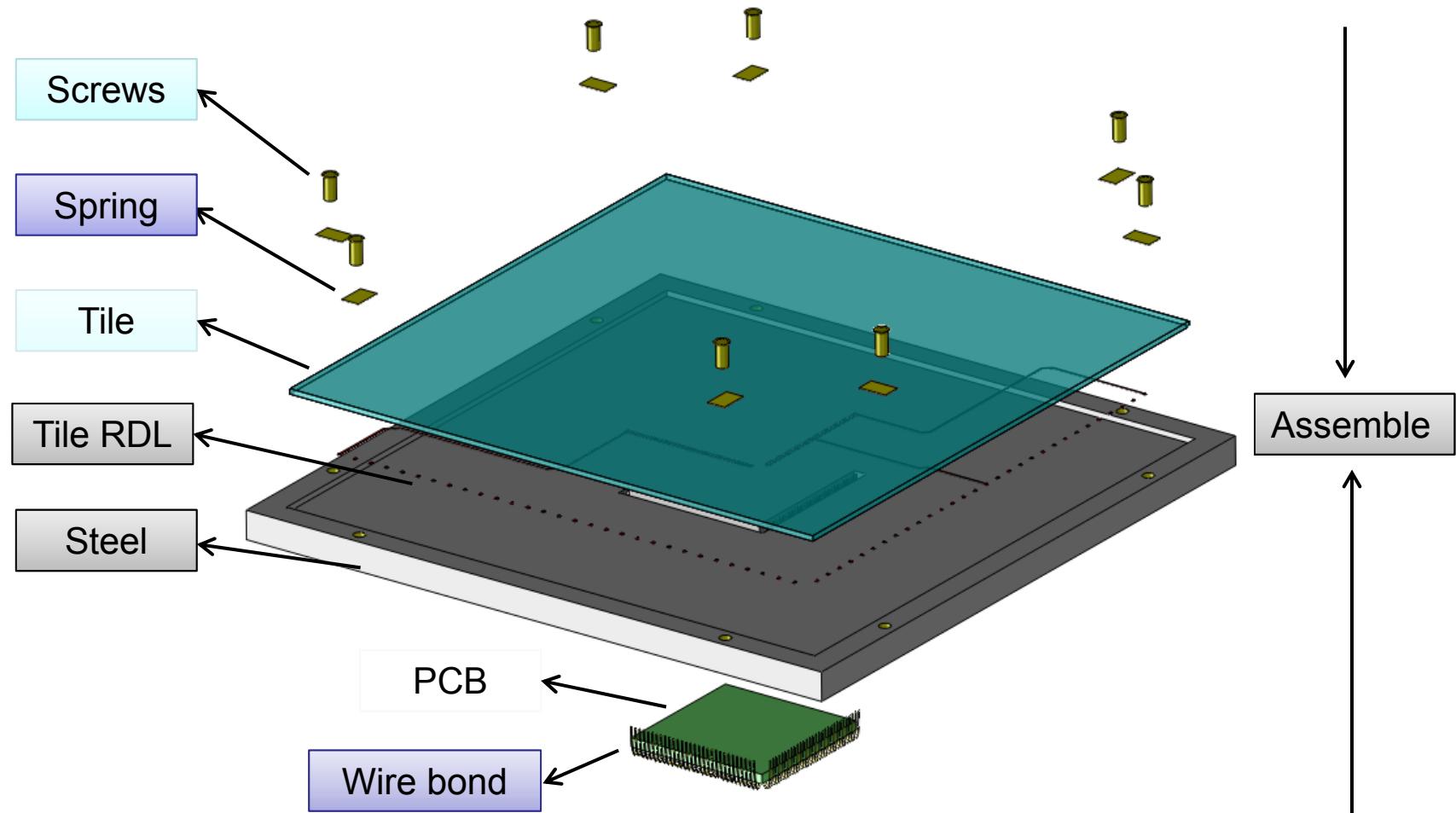
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ASIC nEXO_v1 Test Board

- Two different size nEXO_v1 ASIC Test Boards are designed
 - ~ 5cm × 5cm
 - ~ 10cm × 10cm (same as the wafer)
- 5cm×5cm PCB
 - Can verify the backside routing process
 - First impression of the impact of the ground plane vs 10cm×10cm PCB
- 10cm×10cm PCB
 - Better ground shielding
 - Less bonding inductance (smaller PCB needs 3 bondings: TQV pads -> fanout, fanout -> PCB, PCB -> ASIC)

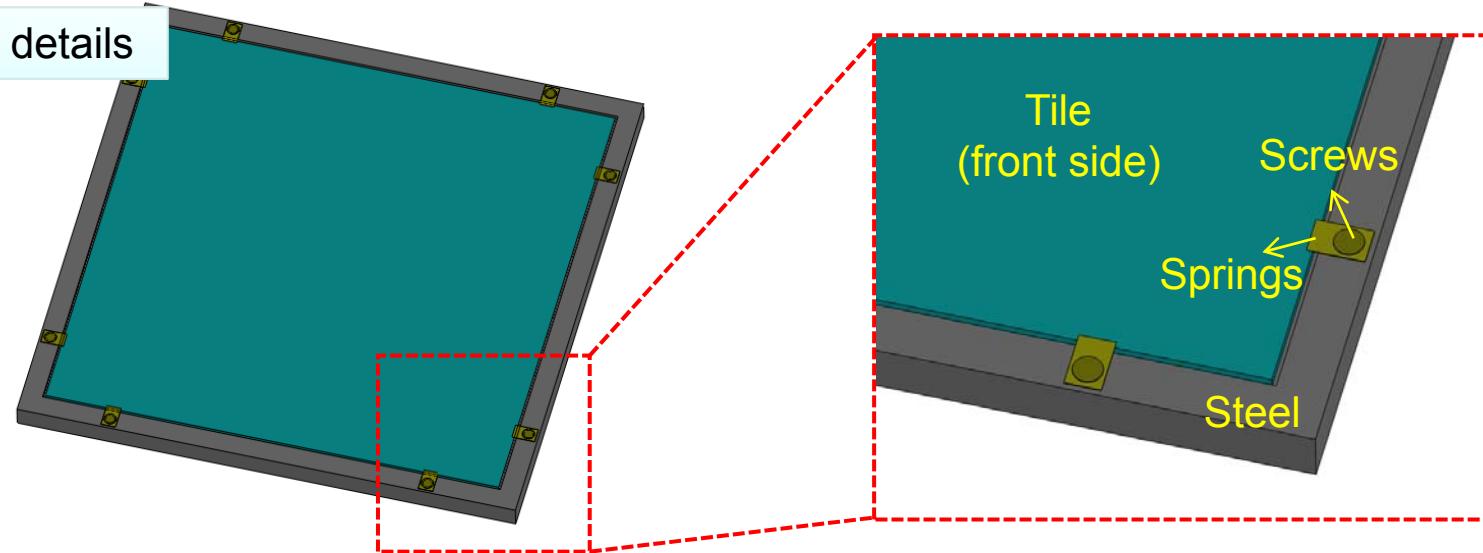


System integration concept



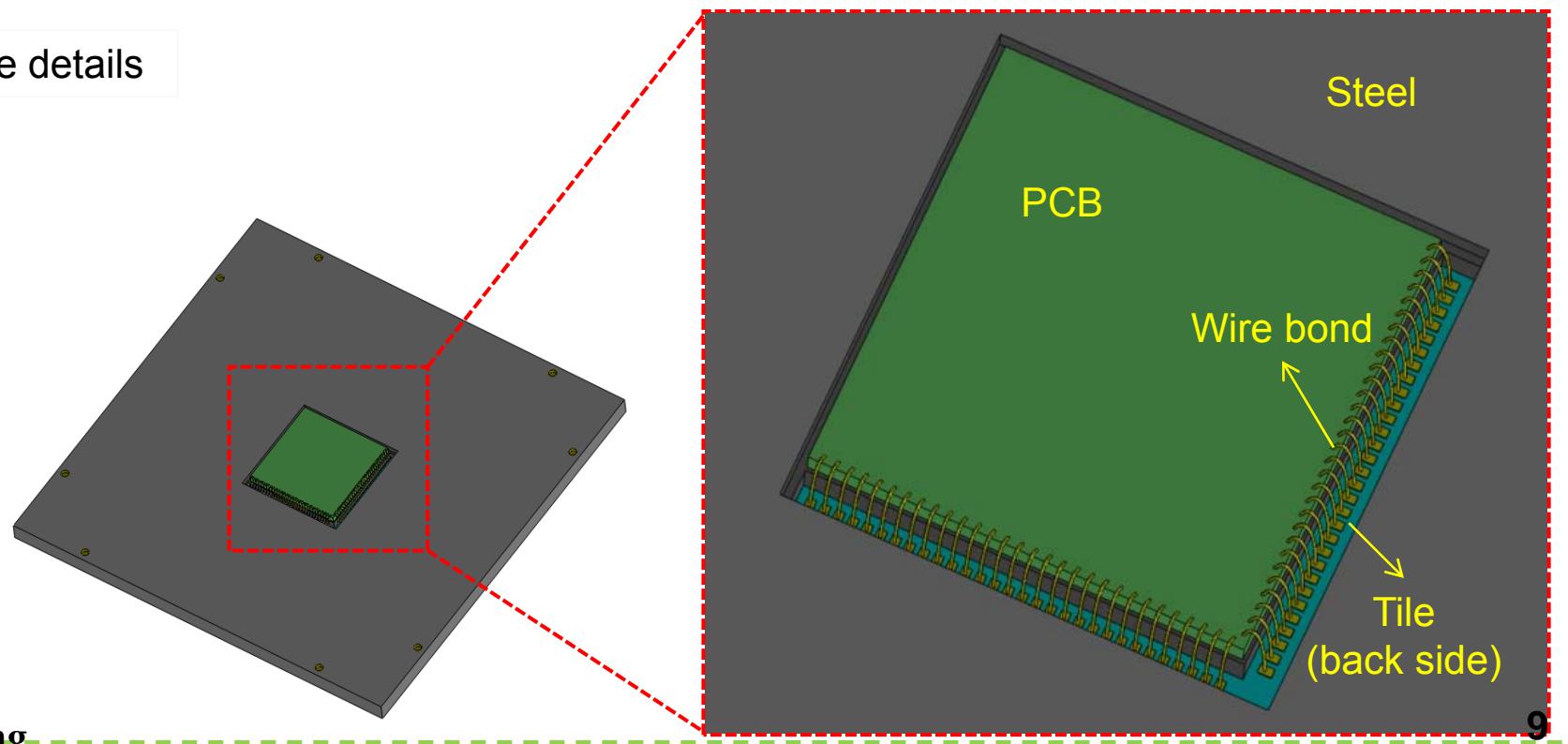
3D of installation

Front side details

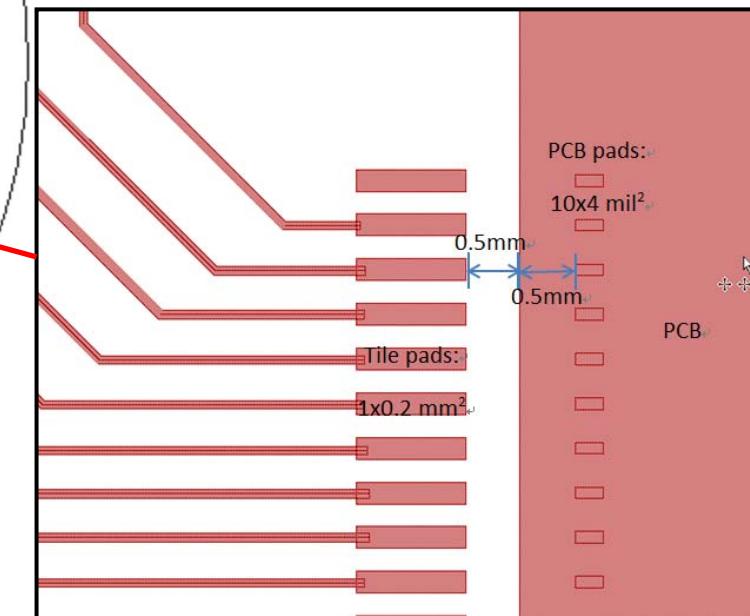
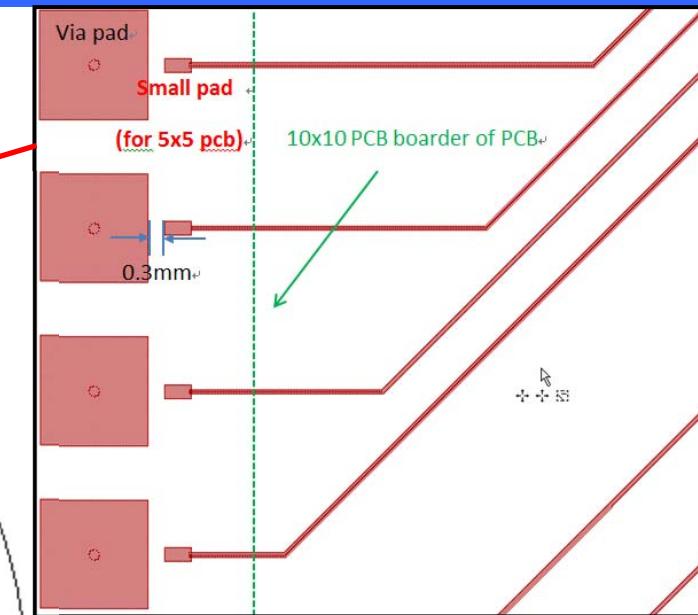
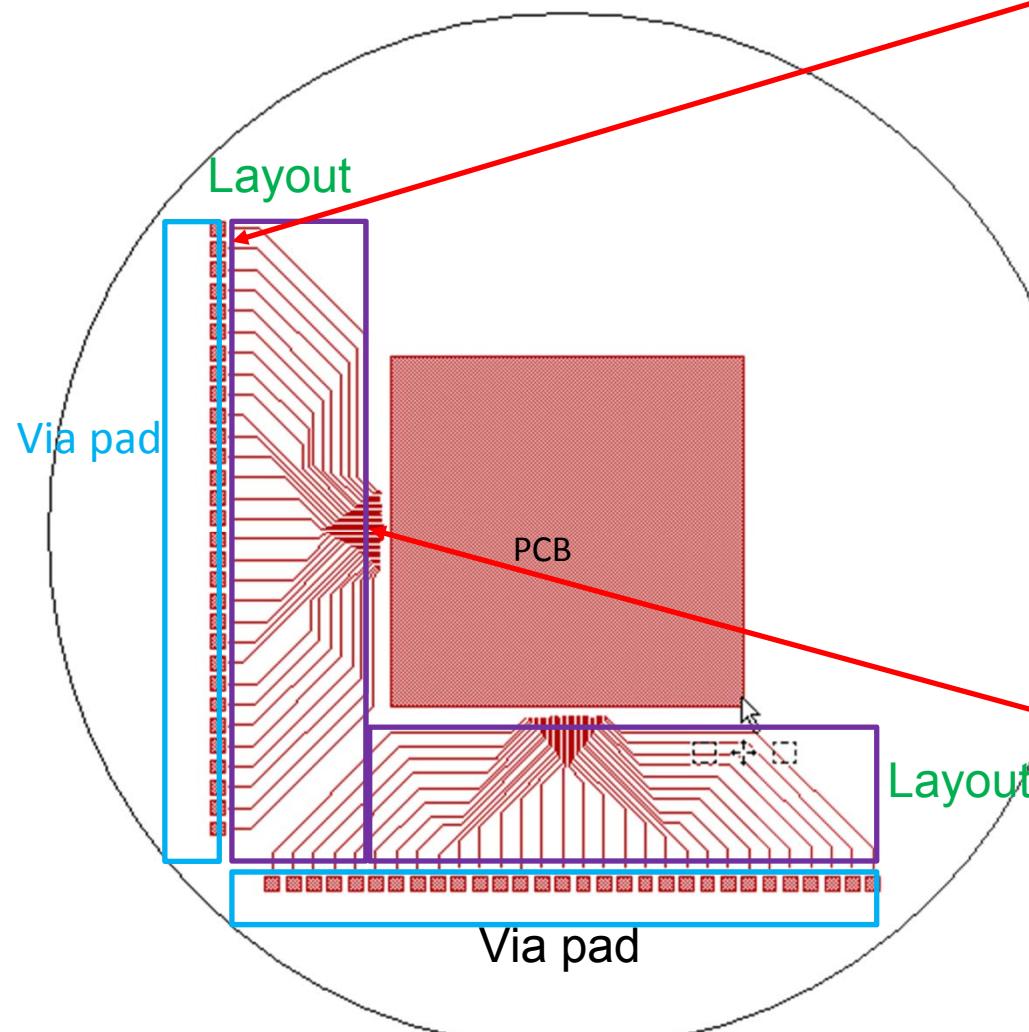


Details

Back side details



Interconnections between PCB & the Tile

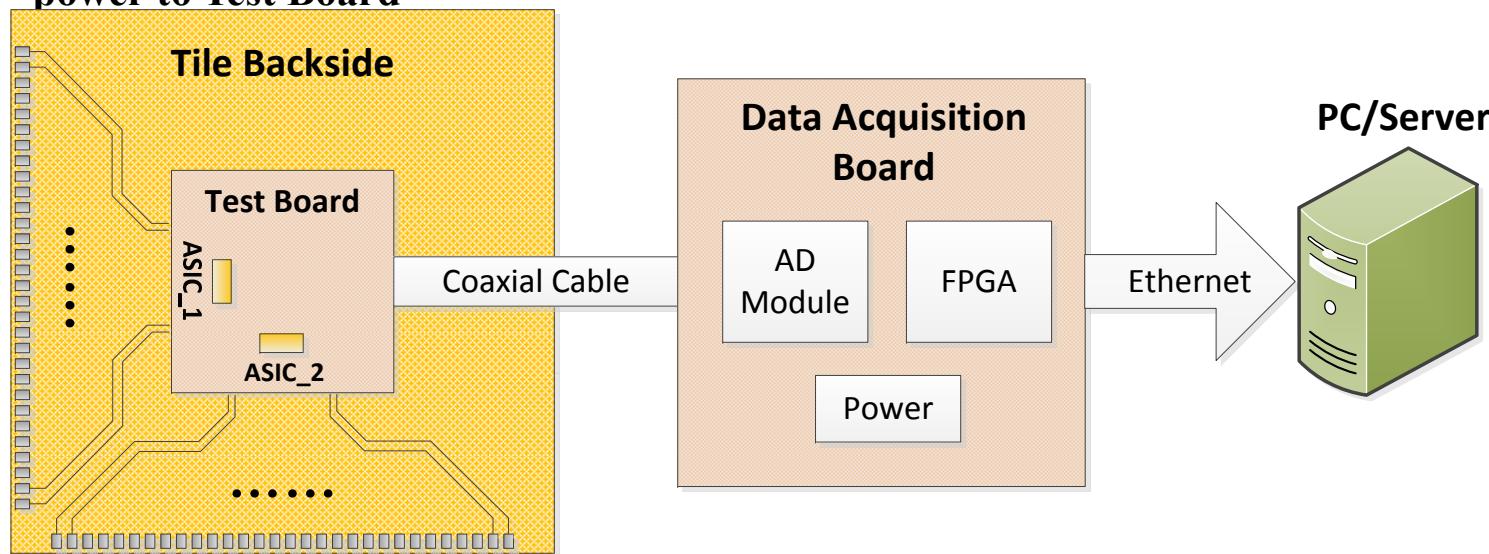


from Qidong

Backend electronics design



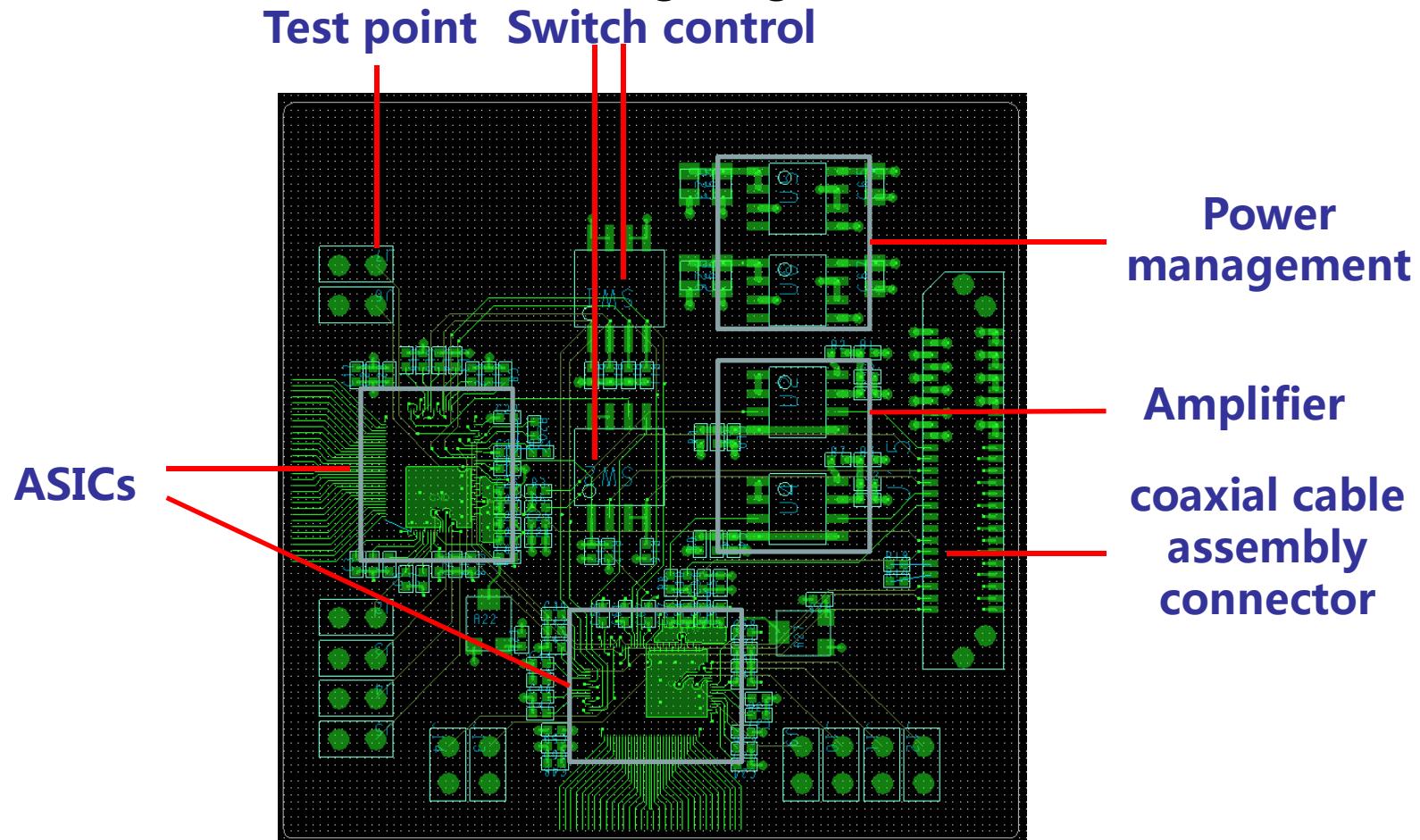
- **nEXO_v1 ASIC Test Board**
 - Two 32-chn nEXO_v1 ASICS on one board
 - 30 horizontal chns + 30 vertical chns
 - Limited numbers of extra components: power + driver
 - To verify the full channel readout first
- **Coaxial Cable**
 - Transfer the analog signal to Data Acquisition Board, as well as providing clock and power to Test Board



Test Board Layout



- 5cm × 5cm 4 layer PCB design
 - All components are placed at the front side of PCB
 - A flat and smooth backside for glueing on the frame



Coaxial Cable Assembly

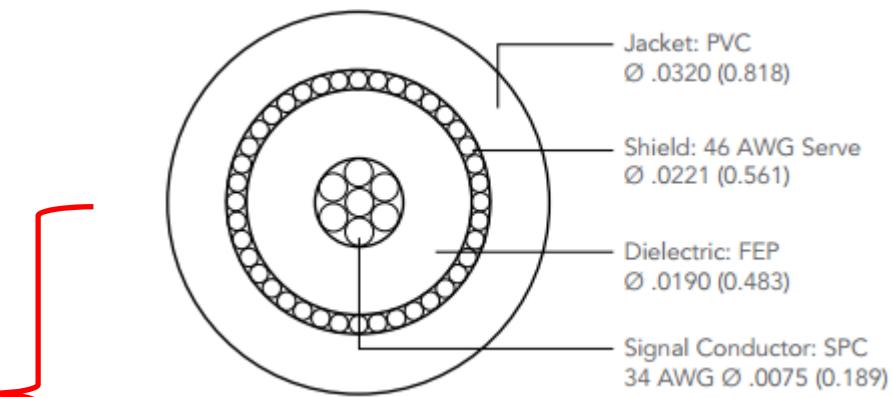
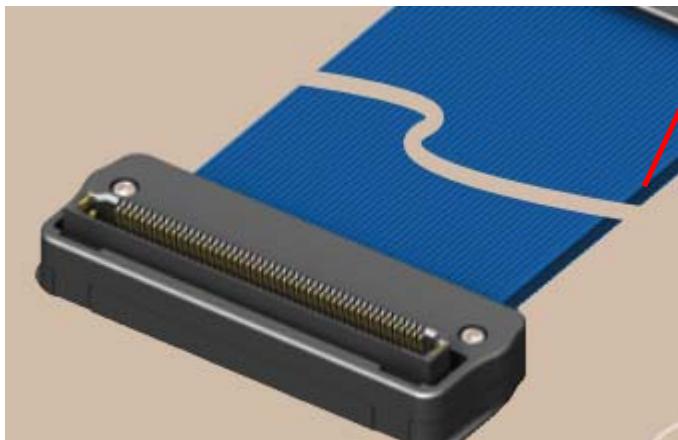


- Prepare two kinds of coaxial cable assemblies
 - ERCD-025-40.00-TTR-TTL-1-D, 0.80 mm edge rate high-speed micro coaxial cable assembly, Samtec.

5 cables for +5V,

5 cables for -5V,(optional)

other cables for signals.



PERFORMANCE DATA

Capacitance:	27 pF/ft (nominal)
Propagation Delay:	1.30 ns/foot
Flex Cycles:	80,000 cycles, 20-wide ribbon*
Current Rating:	Single conductor = 1.8 Amps** 20 conductors = 7.0 Amps**
Shield DCR:	116 Ω/1000 ft
CC DCR:	258 Ω/1000 ft
Min. Bend Radius:	.125"
Availability:	Single, 2-35 ribbon, tape bonded
Temperature Rating:	-25 °C to 105 °C, UL VW-1 Tested ***
DWV Working Voltage:	250 Vt

Coaxial Cable Assembly (subst.)



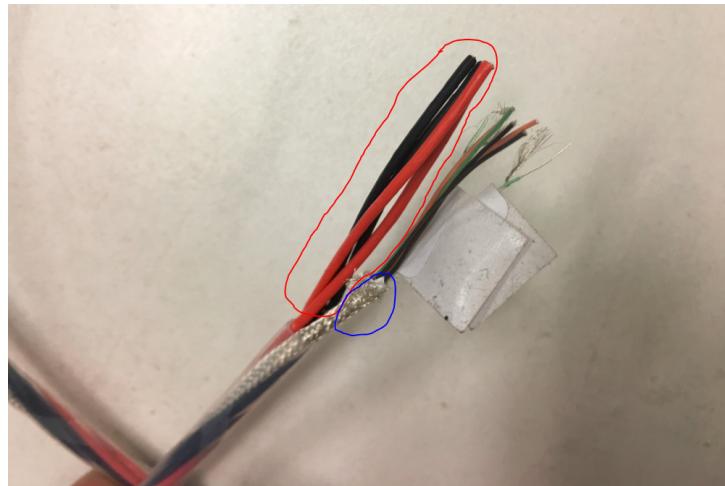
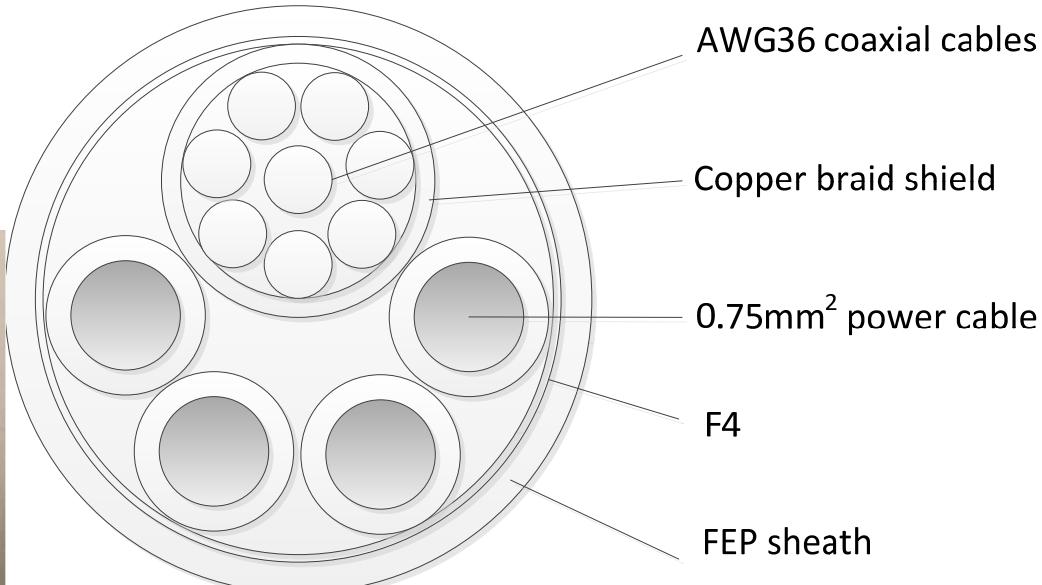
- Custom Coaxial Cable Assembly, Ao Xun Tong Technology Co. Ltd
 - A local Chinese cable vendor

Four 0.75mm² cables for power supply,

8 AWG 36 coaxial cables for signals.

Min. temperature: -55 °C

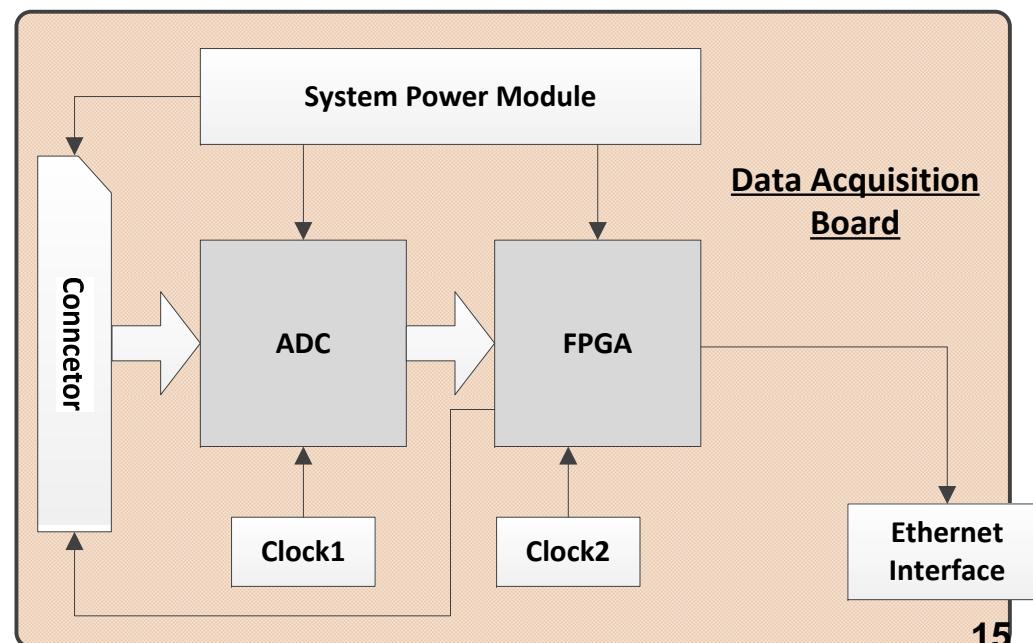
Performance tested and can be customized according to nEXO



Data Acquisition Board



- Data acquisition board designing element list as below
 - Connector: micro-coaxial cables, Samtec
 - ADC: 10-bit with 1.25 Gsps, ADI
 - FPGA: Vertex 5, Xilinx
 - CLK: Frequency range: 125 - 3000 MHz, 78 fs RMS Jitter Generation
 - Clock2: 100MHz OSC
 - Ethernet Interface
 - System Power Module
- PCB is designed



小结及计划



- Backend electronics
 - Design almost ready
 - Full system & debugging will be ready in May
 - Electronics selftest in 2 weeks
- Quartz wafer
 - Waiting for the full recovery of the equipments
 - Processing takes 1~2 month
- System integration & test
 - Full channel readout with a GEM as the source
 - Aiming at testing in LXe in 2018
- Future plans
 - ASIC improvement afterwards
 - Radioactivity test: ASIC + micro-coaxial cables



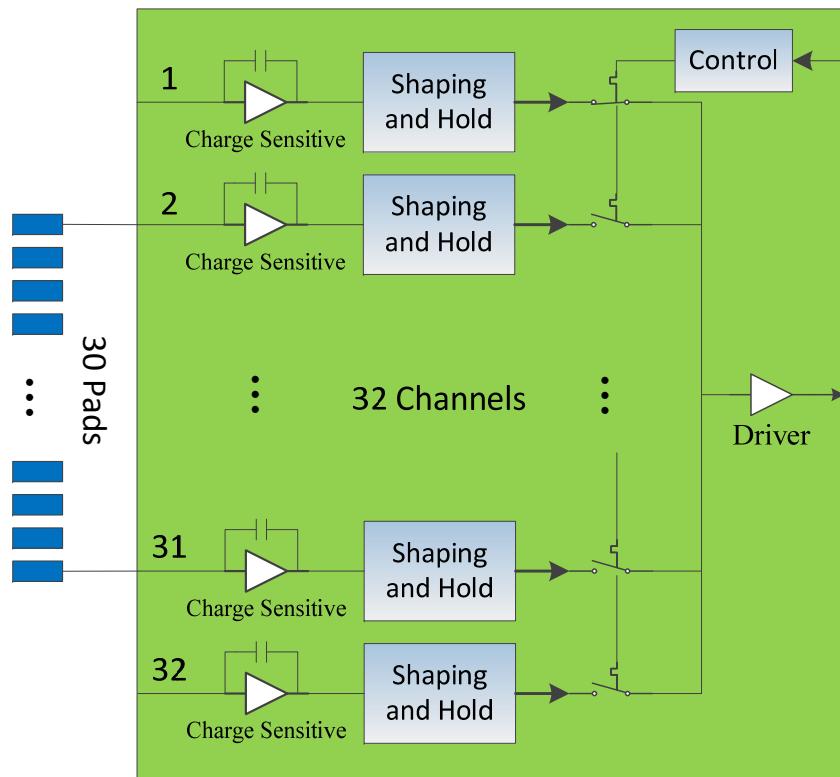
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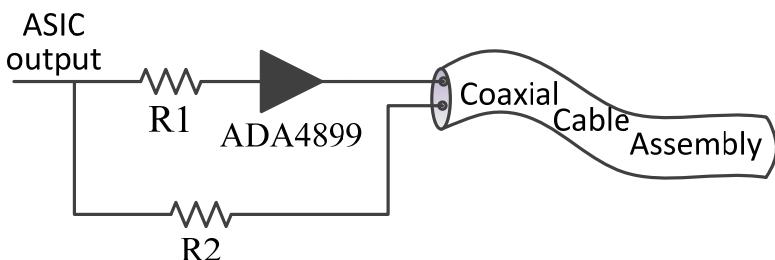
谢谢重点实验室支持/谢谢各位老师

Backup Slides

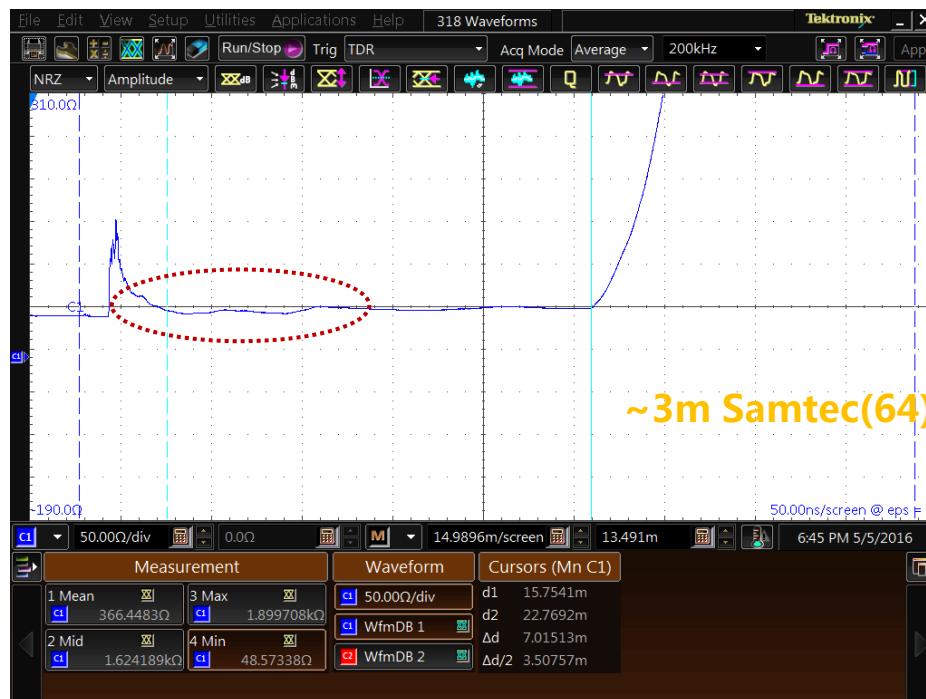
ASIC nEXO_v2 Test Board2



- **nEXO_v2 ASIC inputs**
30 pads on the tile backside input to 30 channels of all the 32 analog input channels of ASIC, 2 channels are reserved.
- **nEXO_v2 ASIC output**
The ASIC output signal to Coaxial Cable by two ways.
 - Directly output to cable
 - After driven by a amplifier (ADA4899)



cables test results



- Micro coaxial cables
- INL<0.08%(AWG cable, ~2m)
- AWG cable shows better transmission characteristics than Samtec cable
- DC resistance may impact the analog signal amplitude
- Radioactivity will be tested later

